

ABSTRACT

The present disclosure relates to a cleaning composition and a method for removing residual polymer film bonding materials on a carrier after mechanical debonding or laser debonding using the same, wherein the cleaning composition at least includes component (A) alkali metal hydroxide (weight percentage concentration: 5%-30%), component (B) polar aprotic solvent (weight percentage concentration: 5%-50%), component (C) co-solvent (weight percentage concentration: 5%-60%) and component (D) water.

(Fig. 1)